



Silicon Carbide Schottky Power Rectifier 30A, 1200V

DESCRIPTION

This 1200 V SiC Schottky rectifier is in a hermetically sealed package and offers very fast switching capabilities. It provides greater efficiency at higher temperatures than competing ultrafast silicon rectifiers.

Important: For the latest information, visit our website <http://www.microsemi.com>.

FEATURES

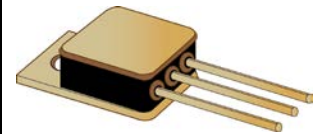
- TO-254 package.
- Lightweight.
- Hermetically sealed package.
- Internal metallurgical bonds.
- High temperature – rated for T_J up to +175 °C.
- Zero reverse recovery current.
- Temperature independent switching behavior.
- Very fast switching compared to fast or ultrafast silicon rectifiers.
- Positive V_F temperature coefficient, better enabling the use of parallel devices for higher currents.
- RoHS compliant version is available.

APPLICATIONS / BENEFITS

- Military, space and other high reliability applications.
- Switching power supplies or other applications requiring extremely fast switching speed and the lowest possible switching losses.
- High forward surge capability.
- High reverse voltage capability with very fast switching.
- Inherently radiation hard (>100 krad/s) as described in Microsemi [MicroNote 050](#).


MAXIMUM RATINGS @ $T_C = +25\text{ °C}$ unless otherwise noted


Parameters/Test Conditions	Symbol	Value	Unit
Junction and Storage Temperature	T_J and T_{STG}	-65 to +175	°C
Thermal Resistance, Junction-to-Case	$R_{\theta JC}$	1.0	°C/W
Working Peak Reverse Voltage	V_{RWM}	1200	V
Non-Repetitive Peak Inverse Voltage	V_{RSM}	1200	V
DC Blocking Voltage	V_{DC}	1200	V
Average DC Output Current @ 25 °C	I_O	30	A
Non-Repetitive Sinusoidal Surge Current @ $t_p = 8.3\text{ ms}$, half sinewave, $I_O = 0$; $V_{RM} = 0$	I_{FSM}	150	A




TO-254 Package

Also available in:

Dual TO-258 package
(leaded)
 [MSiCSE30120CC, CA, and D](#)

TO-204AD (TO-3) package
(leaded)
 [MSiCST30120](#)

U1 package
(surface mount)
 [MSiCSS30120](#)

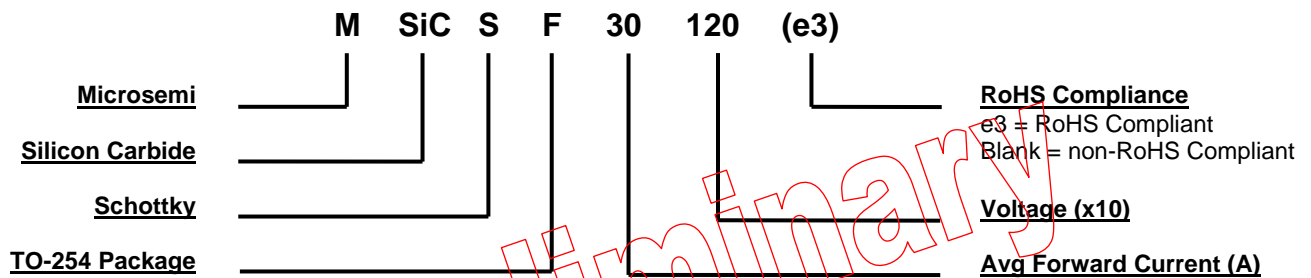
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MECHANICAL and PACKAGING

- CASE: Nickel plated copper base & 1010 steel frame.
- TERMINALS: Solder dipped copper cored 52 alloy or RoHS compliant matte-tin plating.
- MARKING: Alpha numeric.
- POLARITY: See [schematic](#) on last page.
- WEIGHT: Approximately 6.5 grams.
- See [package dimensions](#) on last page.

PART NOMENCLATURE

SYMBOLS & DEFINITIONS

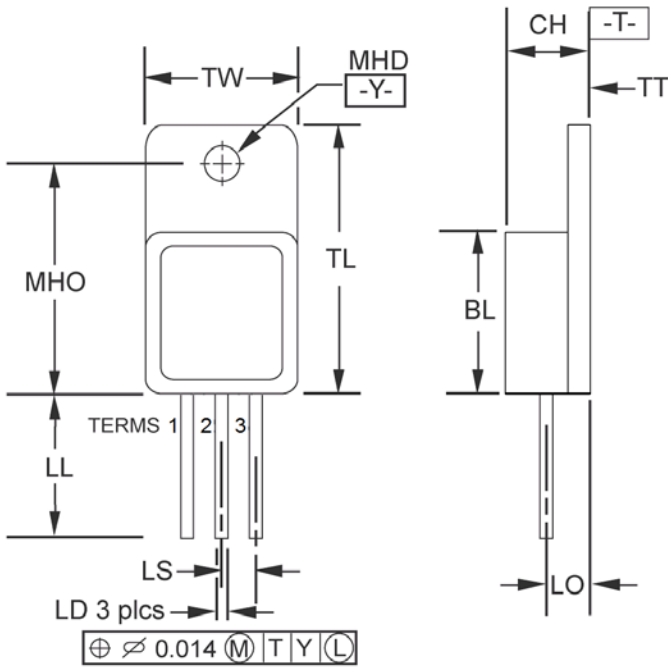
Symbol	Definition
C_J	Junction Capacitance: The junction capacitance in pF at a specified frequency (typically 1 MHz) and specified voltage.
I_F	Forward Current: The forward current dc value, no alternating component.
I_R	Reverse Current: The maximum reverse (leakage) current that will flow at the specified voltage and temperature.
T_J	Junction Temperature: The temperature of a semiconductor junction.
V_F	Forward Voltage: The forward voltage the device will exhibit at a specified current (typically shown as maximum value).
V_R	Reverse Voltage: The reverse voltage dc value, no alternating component.

ELECTRICAL CHARACTERISTICS @ $T_A = +25\text{ }^\circ\text{C}$ unless otherwise noted

Parameters / Test Conditions	Symbol	Min.	Max.	Unit
Forward Voltage* $I_F = 10\text{ A}, T_J = 25\text{ }^\circ\text{C}$ $I_F = 25\text{ A}, T_J = 25\text{ }^\circ\text{C}$ $I_F = 50\text{ A}, T_J = 25\text{ }^\circ\text{C}$	V_F		1.2 1.5 1.8	V
Reverse Current $V_R = 1200\text{ V}, T_J = 25\text{ }^\circ\text{C}$ $V_R = 1200\text{ V}, T_J = 175\text{ }^\circ\text{C}$	I_R		200 500	μA

* Pulse test: Pulse width 300 μsec , duty cycle 2%.

Preliminary

PACKAGE DIMENSIONS


Ltr	Dimensions			
	Inch		Millimeters	
	Min	Max	Min	Max
BL	0.535	0.545	13.59	13.84
CH	0.249	0.260	6.32	6.60
LD	0.035	0.045	0.89	1.14
LL	0.510	0.570	12.95	14.48
LO	0.150 BSC		3.81 BSC	
LS	0.150 BSC		3.81 BSC	
MHD	0.139	0.149	3.53	3.78
MHO	0.665	0.685	16.89	17.40
TL	0.790	0.800	20.07	20.32
TT	0.040	0.050	1.02	1.27
TW	0.535	0.545	13.59	13.84
Term 1	See Schematic			
Term 2	Open (no connection)			
Term 3	See Schematic			

NOTES:

1. Dimensions are in inches.
2. Millimeters are given for information only.
3. In accordance with ASME Y14.5M, diameters are equivalent to Φx symbology.

SCHEMATIC
